



N-Channel 150-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)	
150	0.021 at V _{GS} = 10 V	85	

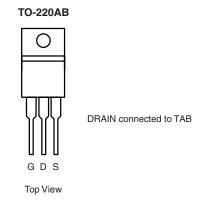
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature



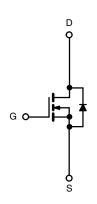
APPLICATIONS

· Primary Side Switch



Ordering Information: SUP85N15-21

SUP85N15-21-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	150	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current (T, = 175 °C)	T _C = 25 °C		85		
Continuous Diam Current (1) = 175 C)	T _C = 125 °C	l _D	50		
Pulsed Drain Current		I _{DM}	180	A	
Avalanche Current		I _{AS}	50		
Single Pulse Avalanche Energy ^b	L = 0.1 mH	0.1 mH E _{AS}		mJ	
b	T _C = 25 °C	В	300 ^c	147	
Maximum Power Dissipation ^b	T _A = 25 °C ^d	P _D	2.4	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient-Free Air	R_{thJA}	62.5	°C/W	
Junction-to-Case (Drain)	R _{thJC}	0.4		

Notes:

- a. Package limited.
- b. Duty cycle ≤ 1 %.
- c. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

SUP85N15-21

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Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Static				<u> </u>		
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	150			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
	I _{DSS}	V _{DS} = 120 V, V _{GS} = 0 V, T _J = 125 °C			50	
		V _{DS} = 120 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 30 A		0.0175	0.021	Ω
	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C			0.042	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C			0.055	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S
Dynamic ^b	•					
Input Capacitance	C _{iss}			4750		pF
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		530		
Reverse Transfer Capacitance	C _{rss}			220		
Total Gate Charge ^c	Qg			76	110	nC
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		21		
Gate-Drain Charge ^c	Q _{gd}			26		
Turn-On Delay Time ^c	t _{d(on)}			22	35	- ns
Rise Time ^c	t _r	V_{DD} = 75 V, R_L = 0.9 Ω I_D \cong 85 A, V_{GEN} = 10 V, R_G = 2.5 Ω		170	250	
Turn-Off Delay Time ^c	t _{d(off)}			40	60	
Fall Time ^c	t _f			170	250	
Source-Drain Diode Ratings and Cha	<u> </u>	(T _C = 25 °C) ^b				
Continuous Current	I _S				85	
Pulsed Current	I _{SM}				180	A
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}	1 200		130	200	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/μs		8	12	A
Reverse Recovery Charge	Q _{rr}	-		0.52	1.2	μC

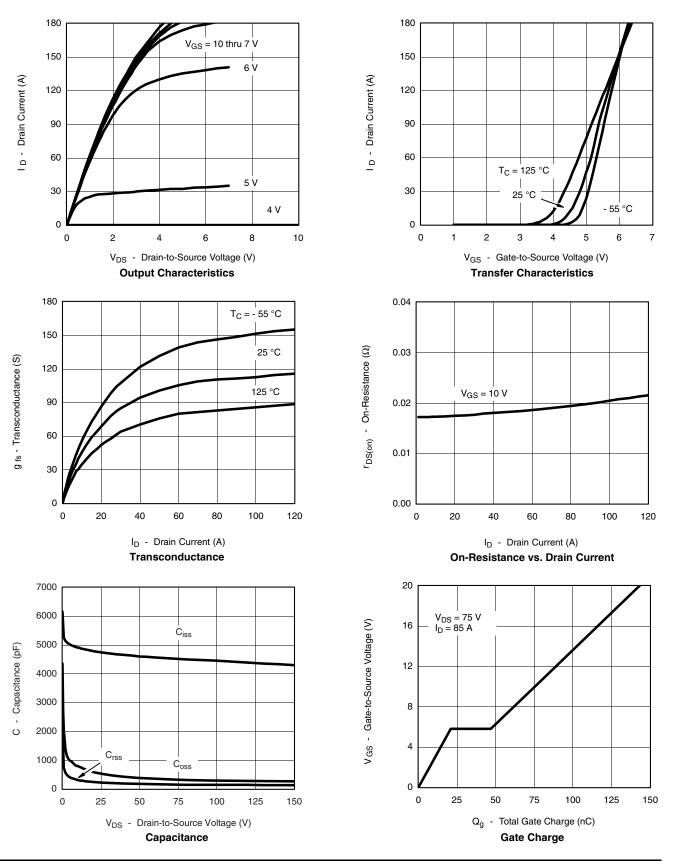
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



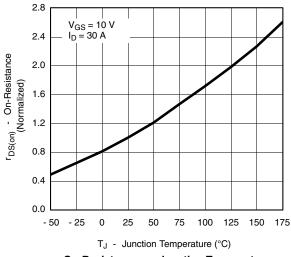
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



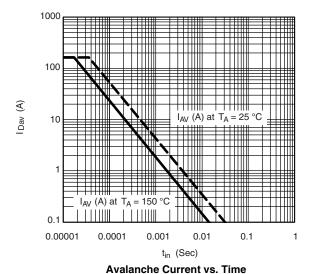
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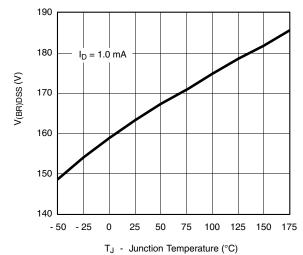
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On-Resistance vs. Junction Temperature



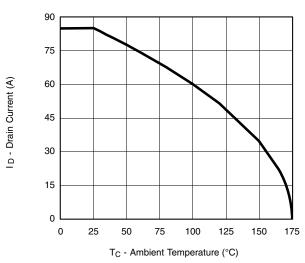
Source-Drain Diode Forward Voltage



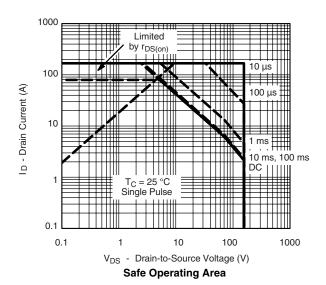
Drain Source Breakdown vs.
Junction Temperature

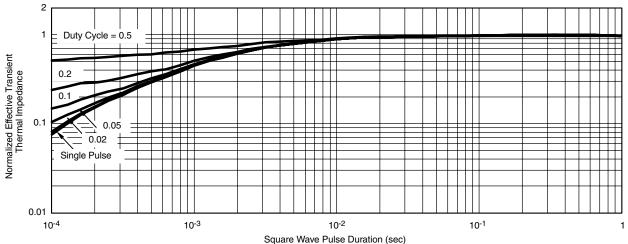


THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature





Normalized Thermal Transient Impedance, Junction-to-Case

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